

SERIES 5600CS STANDALONE. AUTOMATIC. BONDTESTER.



ENGLISH

56
SERIES

BONDING THE STARS

FAS
BONDTEC

SERIES 5600CS

YOU NEED:

- >> Reproducible pull- and shear-results without user influences
- >> Better CPK through stabil testing processes
- >> Clock pulse optimization and automatisaton e.g. for lower cost
- >> Fully automatic non-destructive testing of all bond connections
- >> Availability of all datas for quality assurance and traceability
- >> Compliant pulltesting results according to DVS-2811 and ASTM



THE SOLUTION: **SERIES 5600CS**

- >> Fully automatic pull- & shear-testing by using most modern Pattern-Recognition-Software
- >> Easy programable test process and import of existing bond programs
- >> Process accompanying automatic sequences with a minimum of user efforts
- >> Reproducible test results and precision within a few μm
- >> Automatically rotating and positioning of pull hooks and shear tools even on fine pitch application
- >> Patented technology for compliant pullforce and calculation of values for source and destination bond

56
SERIES



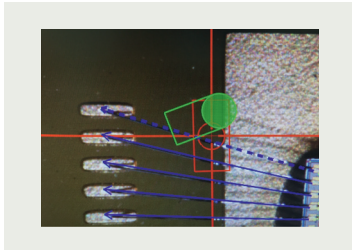
PH100 – PH 5000

- >> Pull testing of thin/heavy wires and heavy ribbons
- >> Suitable pull hook sizes for wire diameters from 15 µm to 500 µm
- >> Test cartridges for forces up to 50 N, matching to your application
- >> Finely tunable 360° rotation for precise positioning of pull hook to the wire



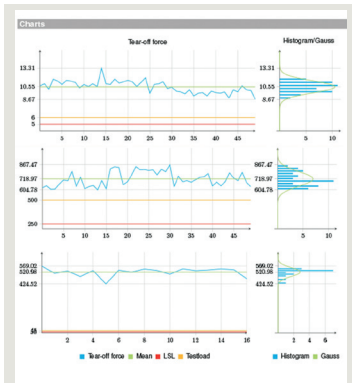
SH500 – SH5000

- >> Shear testing of ball bonds, heavy wires and heavy ribbons
- >> Also suited for SMD- and solder ball shear testing
- >> Test cartridges for forces up to 50 N, matching to your application
- >> Air nozzle for compressed air to remove shear residues and particles



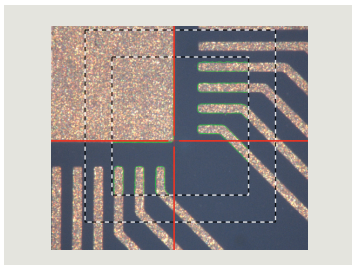
Testing Tool Simulation

- >> Virtual test drive through the whole testing program
- >> Proof of free room for placing and rotating the pullhook overlayed on the live picture
- >> Alignment of the tool position for shear testing



CSR – Corporate Standard Report

- >> Data analysis even for largest data sets from bond testing in series production
- >> Clear data base structure and selection of test samples offering wide filtering options
- >> On-screen display, analysis and configurable reports
- >> Statistical analysis (Min, Max, average and standard deviation)
- >> Cp/Cpk process control, SPC and trend analysis
- >> Export of filtered test data for external analysis
- >> Automatic angle correction during pull testing for standard-compliant testing



PRU – Pattern Recognition Unit

- >> Recognition of position marks for automatic alignment of the testing program
- >> Independently tunable lighting systems
- >> Digital filters for optimization of recognition results
- >> Proofed in our wire bonding systems for a wide range of surfaces



5600 – Pull- & Sheartester

- >> Manual testing of thin- and heavy wire bonds
- >> Easily changeable cartridges



5600C – Automatic Pull- & Sheartester

- >> Test head with changeable cartridges
- >> Camerasystem for automatic testing
- >> Analysis software

Changeable heads for the Series 56 wirebonder!

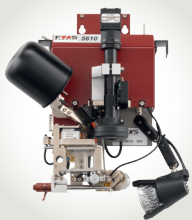
You plan to use wire bonding processes and you need powerful systems?

This is where we come in, with our worldwide unique solution. Developed for unrivalled bonding head exchange, the 56 series allows a machine transition in max. 2 minutes and offers all the features of a fully automatic production equipment with manual loading. Thin wires (diameter: 17 μm to 75 μm), heavy wires (diameter: 100 μm to 500 μm) and ribbons (thin and heavy ribbons) can be processed on one machine base. In addition to that pull and shear tests, heads for all bonding technologies are available

- >> Full-fledged production solution, that can easily compete with a fully automatic machine
- >> Single-Wire, Multi-Wire and Repair-Bonding
- >> Intuitive programming optimized for mouse based use
- >> Advanced usability through dynamic graphical visualization (e.g. influence of looping parameters)
- >> Powerful Pattern Recognition for precise automatic alignment and wire bonding results
- >> All-in-one solution from prototyping to small series production.

You need larger and even more powerful manufacturing capabilities? Look at our 58xx-series!

Series 56



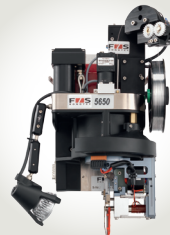
5610
Ball-Wedge



5630
Wedge-Wedge



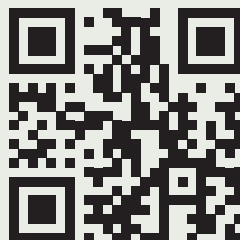
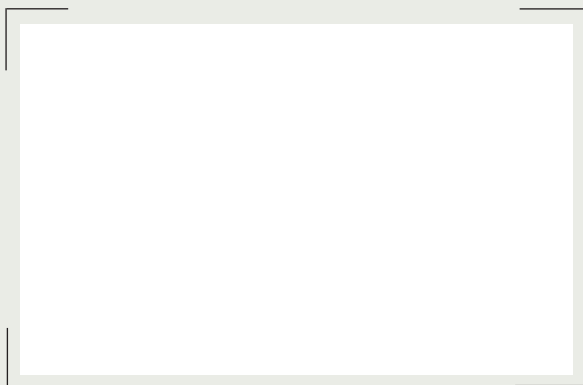
5632
Deep-Access
Wedge/Ribbon



5650/HR
Heavy-Wire &
Heavy-Ribbon



5600C
Fully automatic
Bondtester



F&S BONDTEC
Semiconductor GmbH
Industriezeile 49a
5280 Braunau am Inn
AUSTRIA

ISO-9001/2008-certified

Phone: +43-7722-67052-8270

Fax: +43-7722-67052-8272

E-Mail: info@fsbondtec.at

www.fsbondtec.at

BONDING THE STARS

F S
BONDTEC